

V_{RRM} = 4500 V
 $I_{F(AV)M}$ = 275 A
 I_{FSM} = $5.8 \cdot 10^3$ A
 V_{FO} = 1.67 V
 r_F = 3.54 mΩ
 $V_{DC-Link}$ = 2800 V

Fast Recovery Diode

5SDF 03D4502

Doc. No. 5SYA1117-03 Nov. 19

- Patented free-floating technology
- Industry standard housing
- Cosmic radiation withstand rating
- Low on-state and switching losses
- Optimized to use in snubberless operation

Blocking

Maximum rated values¹⁾

Parameter	Symbol	Conditions	5SDF 03D4502		Unit
Repetitive peak reverse voltage	V_{RRM}	$f = 50$ Hz, $t_p = 10$ ms, $T_{vj} = 115$ °C	4500		V
Permanent DC voltage for 100 FIT failure rate	$V_{DC-link}$	Ambient cosmic radiation at sea level in open air.	2800		V

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse leakage current	I_{RRM}	$V_{RRM}, T_{vj} = 115$ °C			8	mA

Mechanical data

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	F_M		14	16	18	kN
Acceleration	a	Device unclamped			50	m/s ²
Acceleration	a	Device clamped			200	m/s ²

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				0.25	kg
Housing thickness	H		25.77		26.42	mm
Pole-piece diameter	D_P			34		mm
Surface creepage distance	D_S		30			mm
Air strike distance	D_a		20			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

ABB Switzerland Ltd, Semiconductors reserves the right to change specifications without notice.



On-state*Maximum rated values¹⁾*

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	I _{F(AV)M}	Half sine wave, T _c = 70 °C			275	A
RMS on-state current	I _{F(RMS)}				435	A
Peak non-repetitive surge current	I _{FSM}	t _p = 10 ms, T _{vj} = 115 °C, sine half wave,			5.8·10 ³	A
Limiting load integral	I ² t	V _R = 0 V, after surge			1.68·10 ⁵	A ² s

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V _F	I _F = 630 A, T _{vj} = 115 °C		3.20	3.90	V
Threshold voltage	V _{F0}			1.45	1.67	V
Slope resistance	r _F	I _F = 200...700 A, T _{vj} = 115 °C		2.78	3.54	mΩ

Turn-on*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward recovery voltage	V _{FRM}	dI _F /dt = 1000 A/μs, T _{vj} = 115 °C		205		V

Turn-off*Maximum rated values¹⁾*

Parameter	Symbol	Conditions	min	typ	max	Unit
Max. decay rate of on-state current	di/dt _{crit}	I _F = 630 A, T _{vj} = 115 °C, V _{DC-Link} = 2800 V			300	A/μs

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	Q _{rr}	I _F = 630 A, V _{DC-Link} = 2700 V,		755	930	μAs
Reverse recovery current	I _{RM}	-di/dt = 250 A/μs, L _{CL} = 300 nH, C _{CL} = 3 μF, R _S = 1.25 Ω,		350	400	A
Turn-off energy	E _{rr}	D _{CL} = 5SDF 08H6005, T _{vj} = 115 °C			1.8	J

Thermal

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T _{vj}		0		115	°C
Storage temperature range	T _{stg}		-40		125	°C

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	R _{th(j-c)}	Double-side cooled F _m = 14... 18 kN			40	K/kW
	R _{th(j-c)A}	Anode-side cooled F _m = 14... 18 kN			80	K/kW
	R _{th(j-c)C}	Cathode-side cooled F _m = 14... 18 kN			80	K/kW
Thermal resistance case to heatsink	R _{th(c-h)}	Double-side cooled F _m = 14... 18 kN			8	K/kW
	R _{th(c-h)}	Single-side cooled F _m = 14... 18 kN			16	K/kW

Analytical function for transient thermal impedance:

$$Z_{\text{th}(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
R _i (K/kW)	25.613	9.407	3.385	1.595
τ _i (s)	0.3743	0.0454	0.0048	0.0013

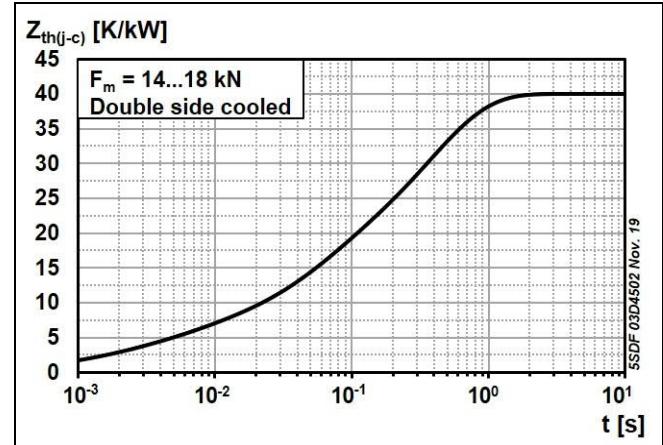


Fig. 1 Transient thermal impedance (junction-to-case) vs. time

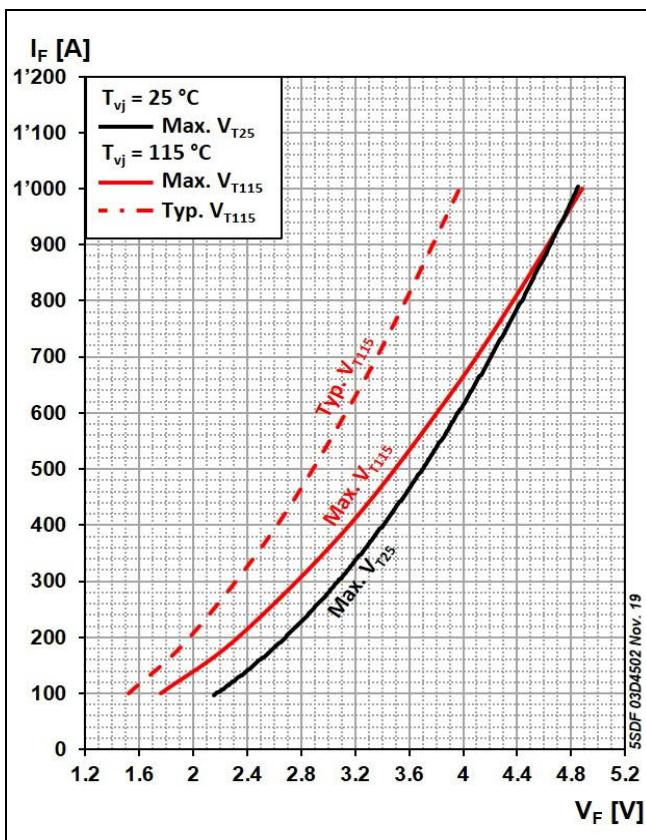


Fig. 2 Forward current vs. forward voltage

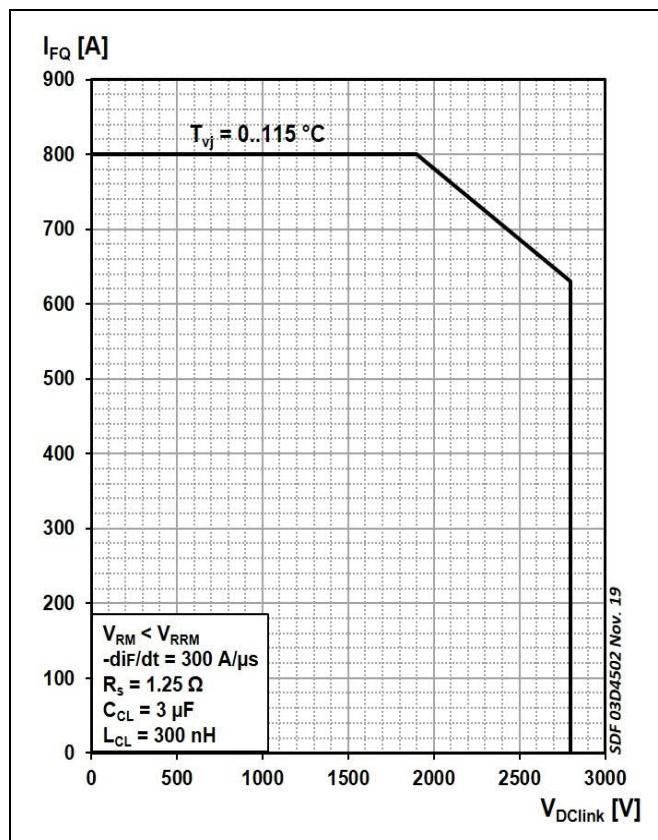


Fig. 3 Diode Safe Operating Area

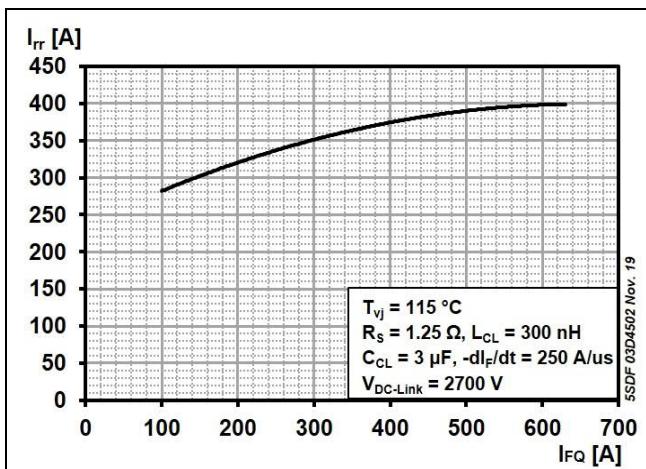


Fig. 4 Diode reverse recovery current vs. turn-off current

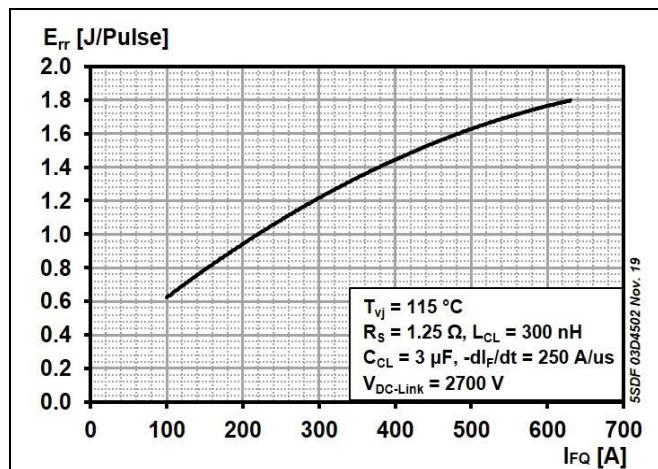


Fig. 5 Diode turn-off energy per pulse vs. turn-off current

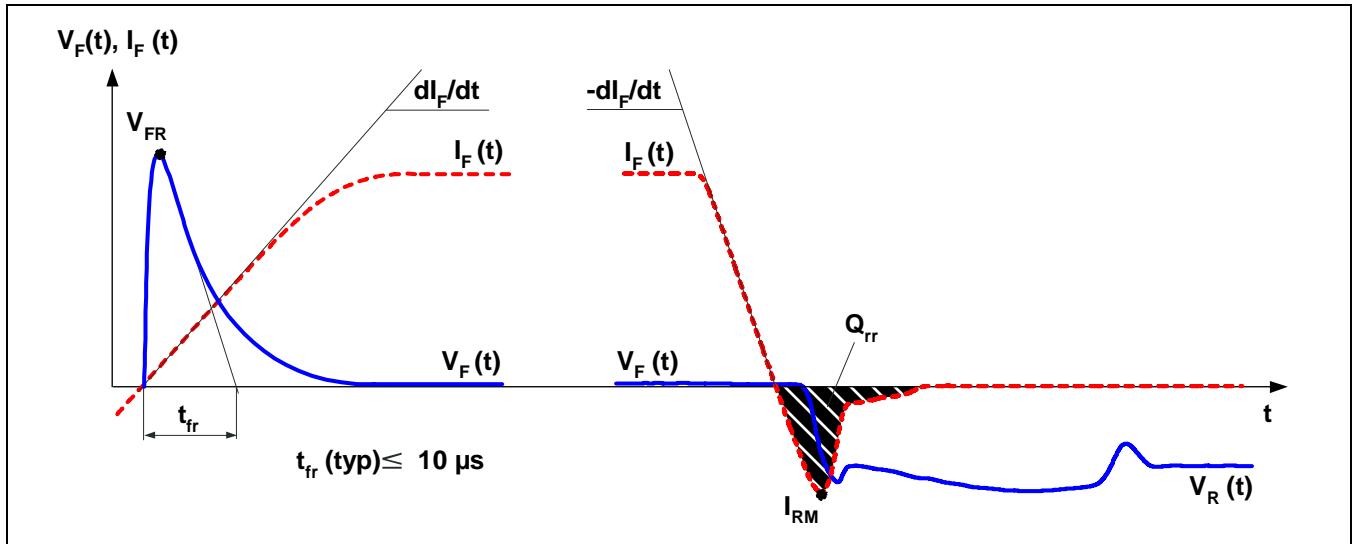


Fig. 6 General current and voltage waveforms

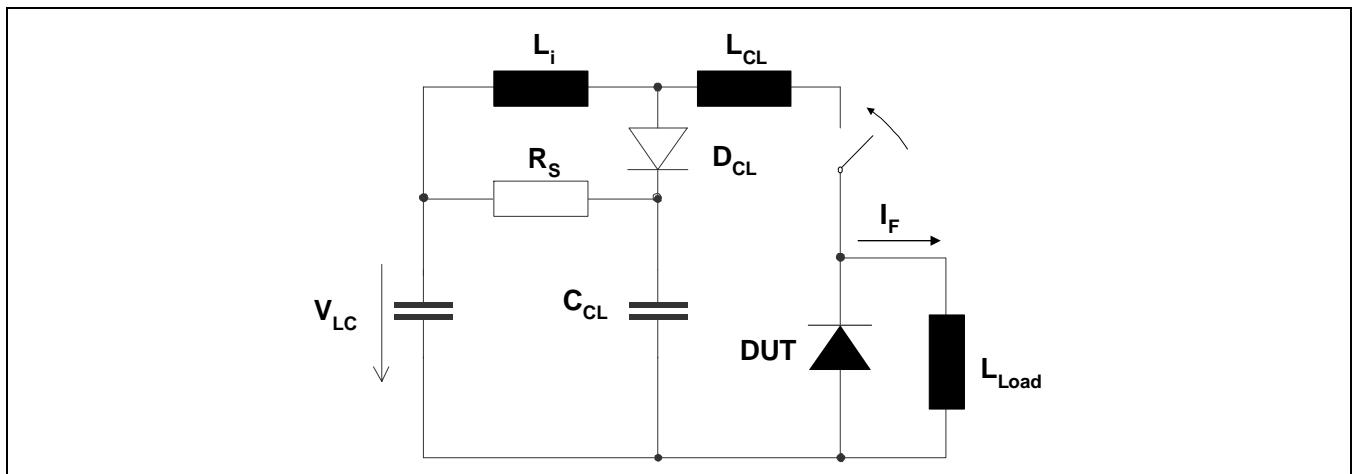


Fig. 7 Test circuit.

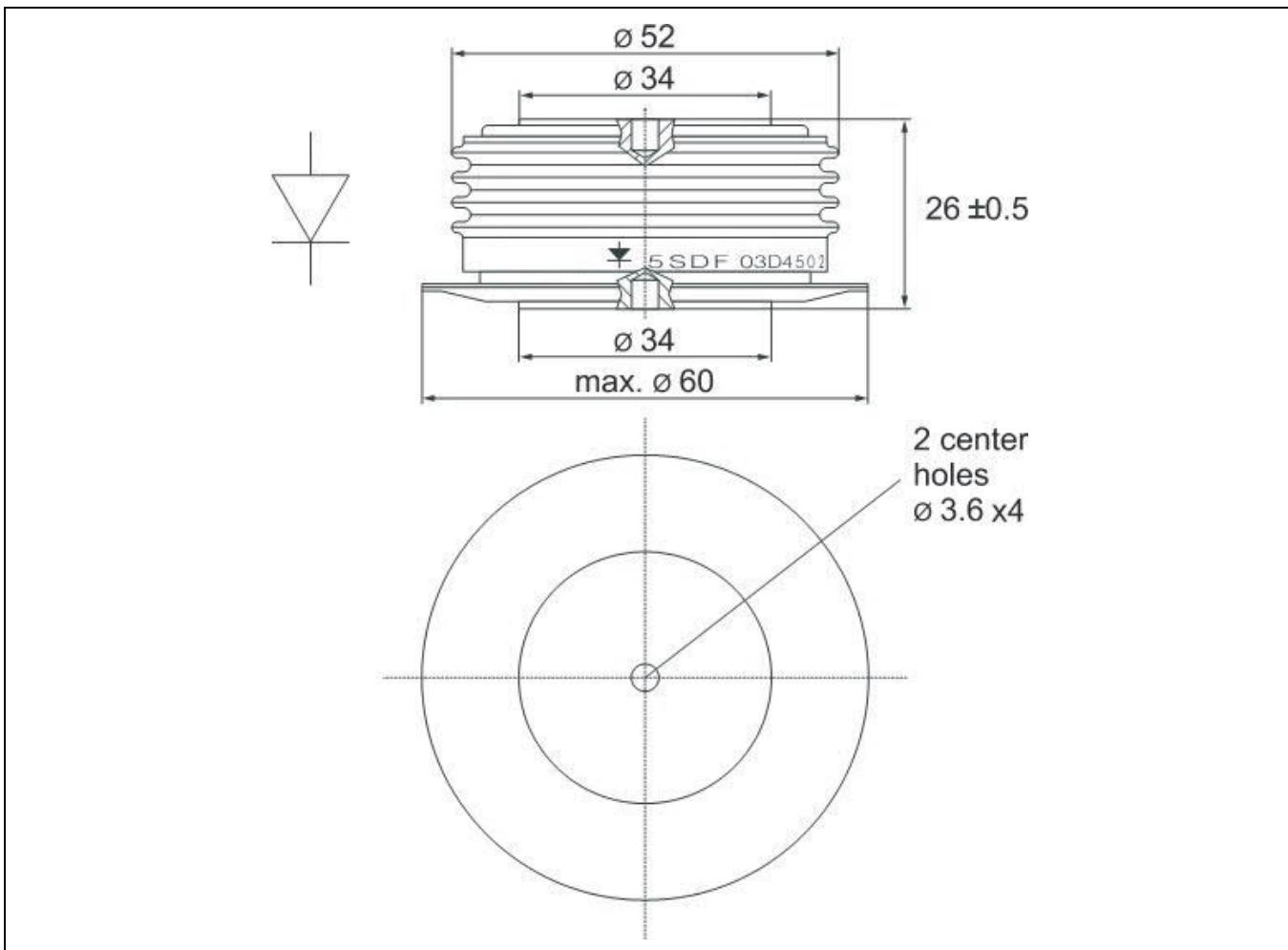


Fig. 8 Device Outline Drawing

Related documents:

Doc. Nr.	Title
5SYA 2036	Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors
5SYA 2064	Applying Fast Recovery Diodes
5SZK 9104	Specification of environmental class for pressure contact diodes, PCTs and GTO, STORAGE
5SZK 9105	Specification of environmental class for pressure contact diodes, PCTs and GTO, TRANSPORTATION
5SZK 9115	Specification of environmental class for presspack Diodes, PCTs and GTOs, OPERATION (Industry)
5SZK 9116	Specification of environmental class for presspack Diodes, PCTs and GTOs, OPERATION (Traction)

Please refer to <http://www.abb.com/semiconductors> for current version of documents.

ABB Switzerland Ltd, Semiconductors reserves the right to change specifications without notice.



**ABB Switzerland Ltd
Semiconductors**
Fabrikstrasse 3
CH-5600 Lenzburg, Switzerland

Doc. No. 5SYA1117-03 Nov. 19

Telephone +41 (0)58 586 1419
Fax +41 (0)58 586 1306
Email abbsem@ch.abb.com
Internet www.abb.com/semiconductors